# P-Channel 150 V (D-S) MOSFET

| PRODUCT SUMMARY | | | |
|---|---|---|---|
| $V_{DS}$ (V) | $R_{DS(on)}$ (Ω) | $I_D$ (A) | $Q_g$ (Typ.) |
| - 150 | 0.065 at $V_{GS}$ = - 10 V | - 40 | 75 nC |
| | 0.070 at $V_{GS}$ = - 4.5 V | - 38 | |

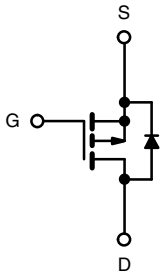
## FEATURES

- Maximum 175 °C junction temperature
- 100 % $R_g$ and UIS tested
- DT-TrenchPower MOSFET

RoHS COMPLIANT
HALOGEN FREE

TO-263


Top View




P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS ($T_A$ = 25 °C, unless otherwise noted) | | | | |
|---|---|---|---|---|
| **Parameter** | | **Symbol** | **Limit** | **Unit** |
| Drain-Source Voltage | | $V_{DS}$ | - 150 | V |
| Gate-Source Voltage | | $V_{GS}$ | ± 20 | |
| Continuous Drain Current ($T_J$ = 150 °C)[b] | $T_C$ = 25 °C | $I_D$ | - 40 | A |
| | $T_C$ = 70 °C | | - 33 | |
| | $T_A$ = 25 °C | | - 12[b, c] | |
| | $T_A$ = 70 °C | | - 8.5[b, c] | |
| Pulsed Drain Current | | $I_{DM}$ | - 155 | |
| Continuous Source Current (Diode Conduction) | $T_C$ = 25 °C | $I_S$ | - 40[a] | |
| | $T_A$ = 25 °C | | - 5.25[b, c] | |
| Avalanche Current | L = 0.1 mH | $I_{AS}$ | - 38 | |
| Single Pulse Avalanche Energy | | $E_{AS}$ | 425 | mJ |
| Maximum Power Dissipation | $T_C$ = 25 °C | $P_D$ | 285 | W |
| | $T_C$ = 70 °C | | 199 | |
| Operating Junction and Storage Temperature Range | | $T_J$, $T_{stg}$ | - 55 to 175 | °C |

| THERMAL RESISTANCE RATINGS | | | | | |
|---|---|---|---|---|---|
| **Parameter** | | **Symbol** | **Typical** | **Maximum** | **Unit** |
| Junction-to-Ambient[a] | t ≤ 10 s | $R_{thJA}$ | 15 | 18 | °C/W |
| | Steady State | | 40 | 50 | |
| Junction-to-Case (Drain) | | $R_{thJC}$ | 0.55 | 1.2 | |

Notes:
a. Package limited.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. Maximum under steady state conditions is 50 °C/W.

| **SPECIFICATIONS** ($T_J$ = 25 °C, unless otherwise noted) | | | | | | |
|---|---|---|---|---|---|---|
| **Parameter** | **Symbol** | **Test Conditions** | **Min.** | **Typ.** | **Max.** | **Unit** |
| **Static** | | | | | | |
| Drain-Source Breakdown Voltage | $V_{DS}$ | $V_{GS}$ = 0 V, $I_D$ = - 250 µA | - 150 | | | V |
| $V_{DS}$ Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D$ = - 250 µA | | - 109 | | mV/°C |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | 5.9 | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$, $I_D$ = - 250 µA | - 1.5 | | - 3.5 | V |
| Gate-Source Leakage | $I_{GSS}$ | $V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$ = - 120 V, $V_{GS}$ = 0 V | | | - 1 | µA |
| | | $V_{DS}$ = - 120 V, $V_{GS}$ = 0 V, $T_J$ = 55 °C | | | - 10 | |
| On-State Drain Current[a] | $I_{D(on)}$ | $V_{DS} \geq$ 5 V, $V_{GS}$ = - 10 V | - 40 | | | A |
| Drain-Source On-State Resistance[a] | $R_{DS(on)}$ | $V_{GS}$ = - 10 V, $I_D$ = - 10 A | | 0.065 | 0.078 | Ω |
| | | $V_{GS}$ = - 4.5 V, $I_D$ = - 8 A | | 0.070 | 0.085 | |
| Forward Transconductance[a] | $g_{fs}$ | $V_{DS}$ = - 15 V, $I_D$ = - 10 A | | 18 | | S |
| **Dynamic[b]** | | | | | | |
| Input Capacitance | $C_{iss}$ | $V_{DS}$ = - 50 V, $V_{GS}$ = 0 V, f = 1 MHz | | 6100 | | pF |
| Output Capacitance | $C_{oss}$ | | | 730 | | |
| Reverse Transfer Capacitance | $C_{rss}$ | | | 85 | | |
| Total Gate Charge | $Q_g$ | $V_{DS}$ = - 50 V, $V_{GS}$ = - 10 V, $I_D$ = - 10 A | | 75 | 110 | nC |
| | | $V_{DS}$ = - 50 V, $V_{GS}$ = - 4.5 V, $I_D$ = - 8 A | | 34 | 50 | |
| Gate-Source Charge | $Q_{gs}$ | | | 14 | | |
| Gate-Drain Charge | $Q_{gd}$ | | | 26 | | |
| Gate Resistance | $R_g$ | f = 1 MHz | | 5 | | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD}$ = - 50 V, $R_L$ = 6.5 Ω<br>$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 Ω | | 25 | | ns |
| Rise Time | $t_r$ | | | 70 | | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 43 | | |
| Fall Time | $t_f$ | | | 40 | | |
| **Drain-Source Body Diode Characteristics** | | | | | | |
| Continuous Source-Drain Diode Current | $I_S$ | $T_C$ = 25 °C | | | - 40 | A |
| Pulse Diode Forward Current[a] | $I_{SM}$ | | | | - 155 | |
| Body Diode Voltage | $V_{SD}$ | $I_S$ = - 7.7 A | | - 0.8 | - 1.2 | V |
| Body Diode Reverse Recovery Time | $t_{rr}$ | $I_F$ = - 7.7 A, dI/dt = 100 A/µs, $T_J$ = 25 °C | | 60 | 90 | ns |
| Body Diode Reverse Recovery Charge | $Q_{rr}$ | | | 150 | 225 | nC |
| Reverse Recovery Fall Time | $t_a$ | | | 46 | | ns |
| Reverse Recovery Rise Time | $t_b$ | | | 14 | | |

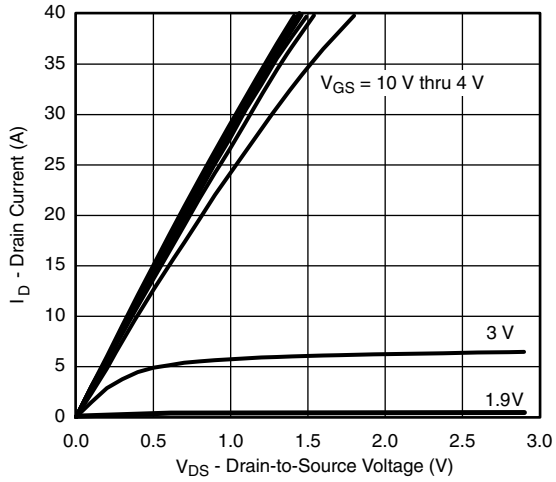
Notes:

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

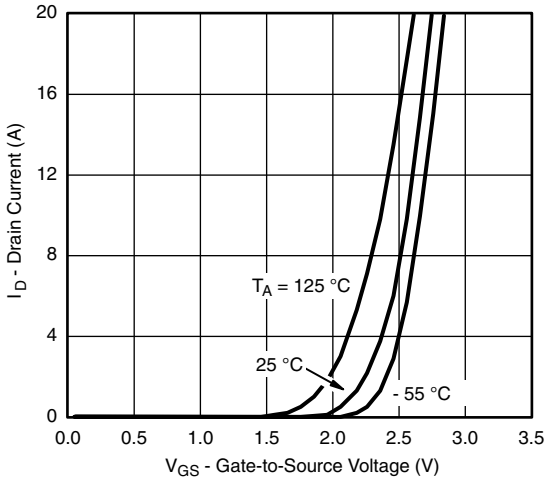
b. Guaranteed by design, not subject to production testing.

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

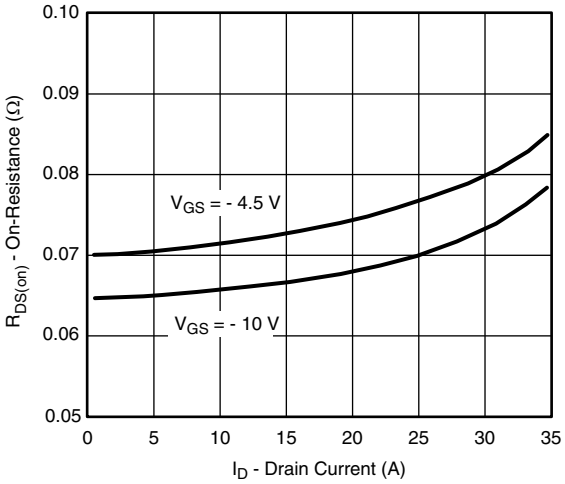
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



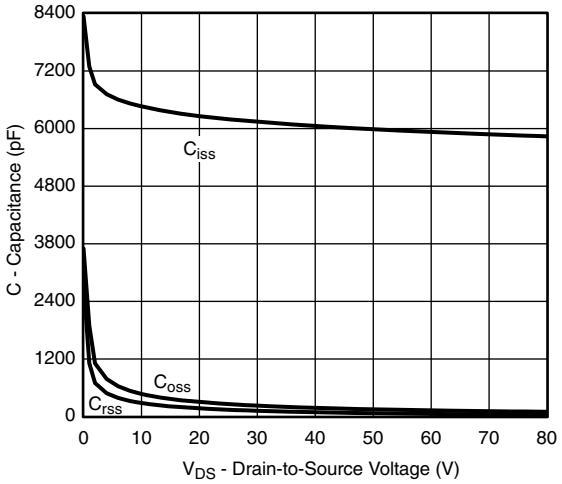

**Output Characteristics**



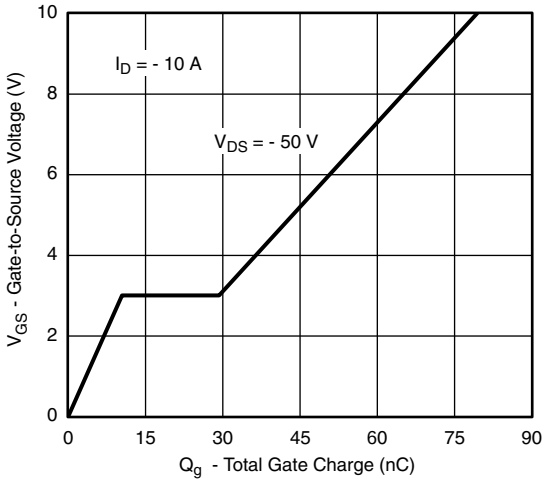

**Transfer Characteristics**



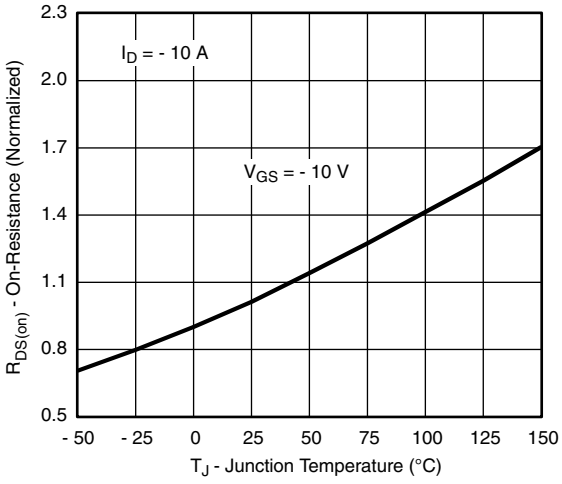

**On-Resistance vs. Drain Current and Gate Voltage**




**Capacitance**

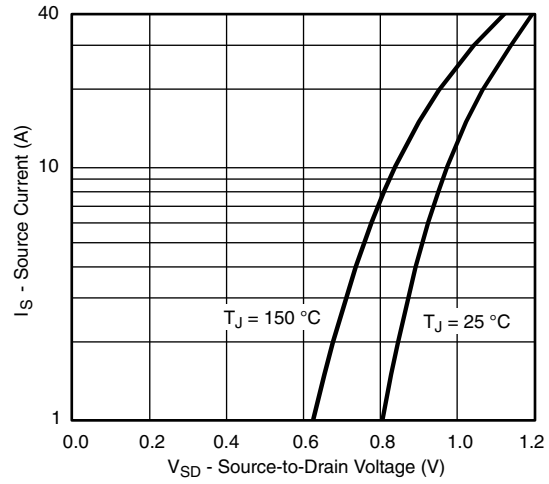



**Gate Charge**

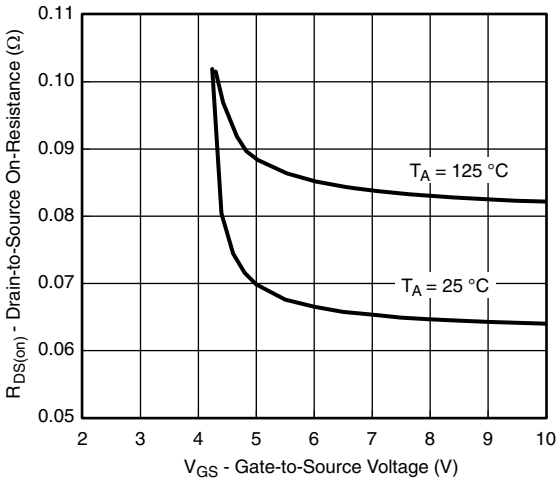



**On-Resistance vs. Junction Temperature**

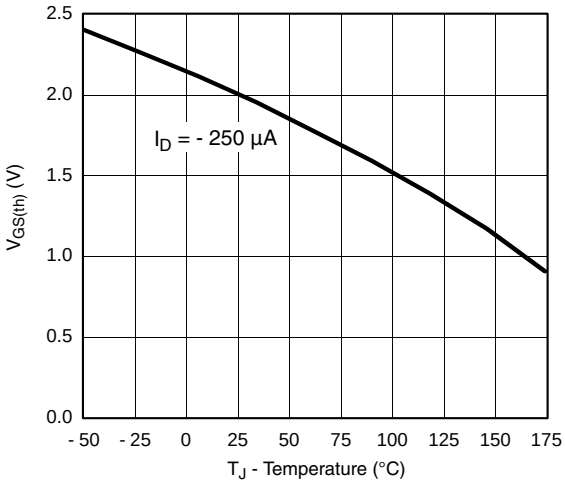
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



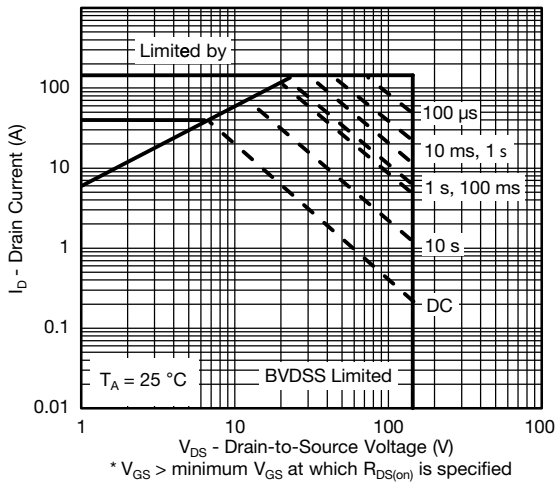

**Source-Drain Diode Forward Voltage**



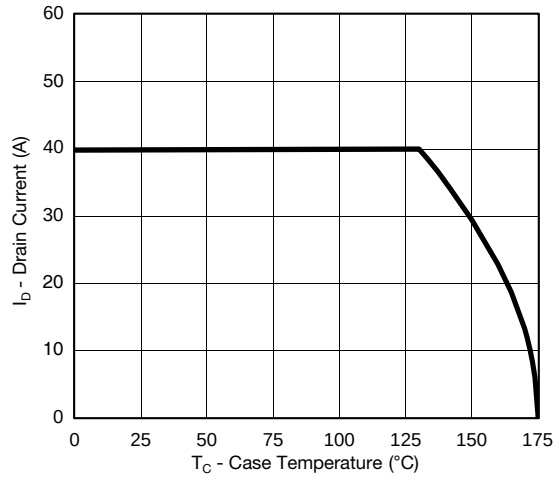

**On-Resistance vs. Gate-to-Source Voltage**



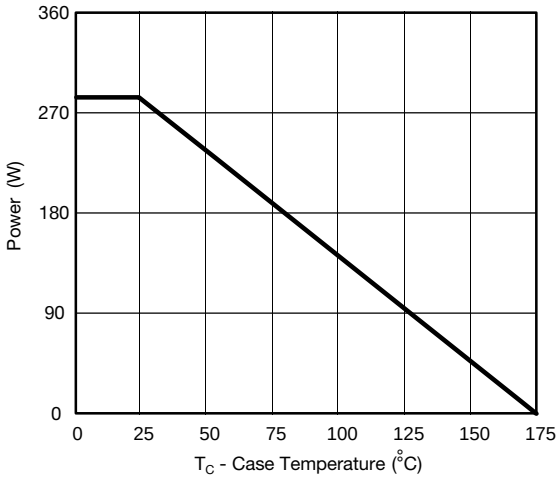

**Threshold Voltage**




**Safe Operating Area, Junction-to-Ambient**

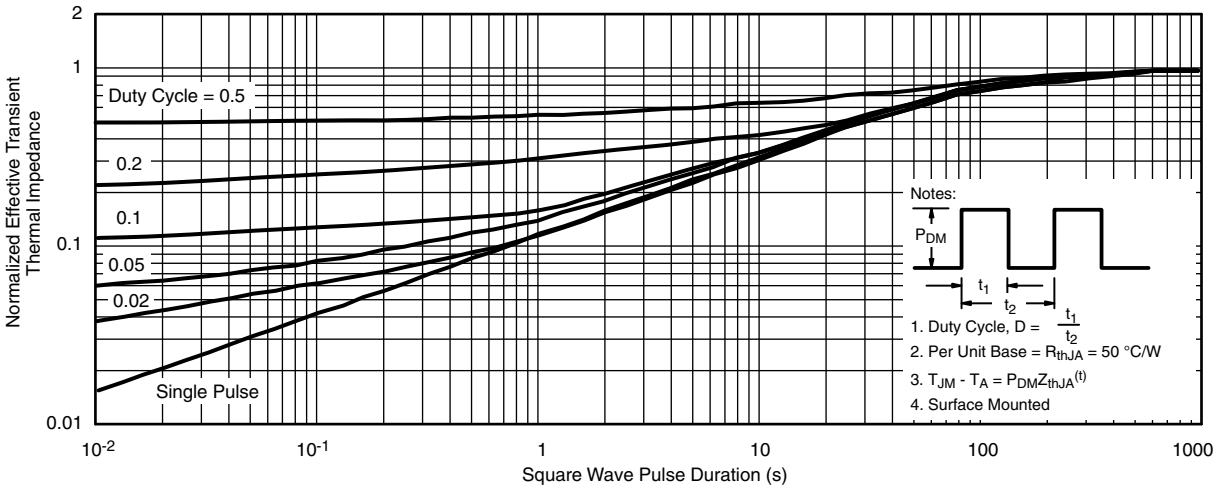



**Current Derating***

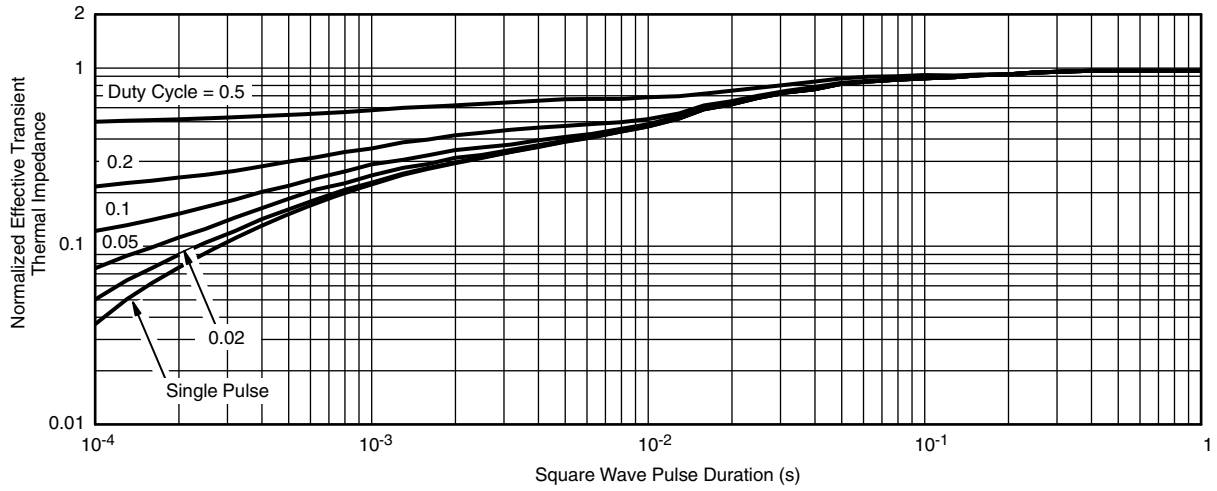



**Single Pulse Power, Junction-to-Ambient**

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

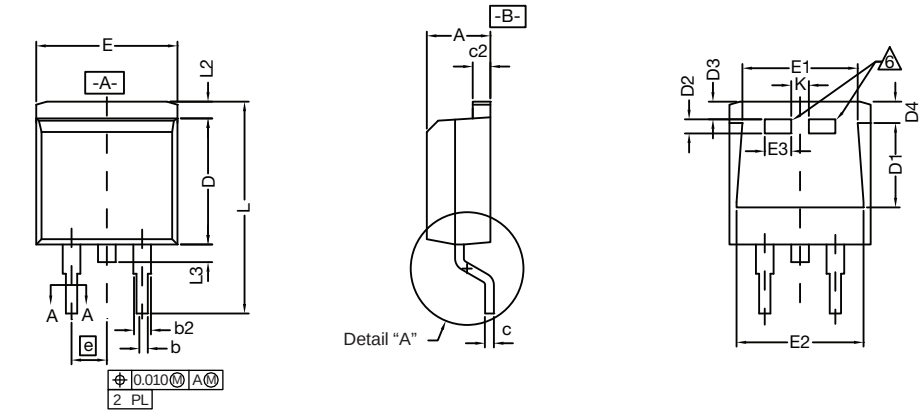


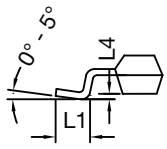

**Normalized Thermal Transient Impedance, Junction-to-Ambient**



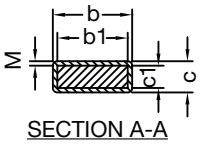

**Normalized Thermal Transient Impedance, Junction-to-Case**

# TO-263 ($D^2PAK$): 3-LEAD




DETAIL A (ROTATED 90°)



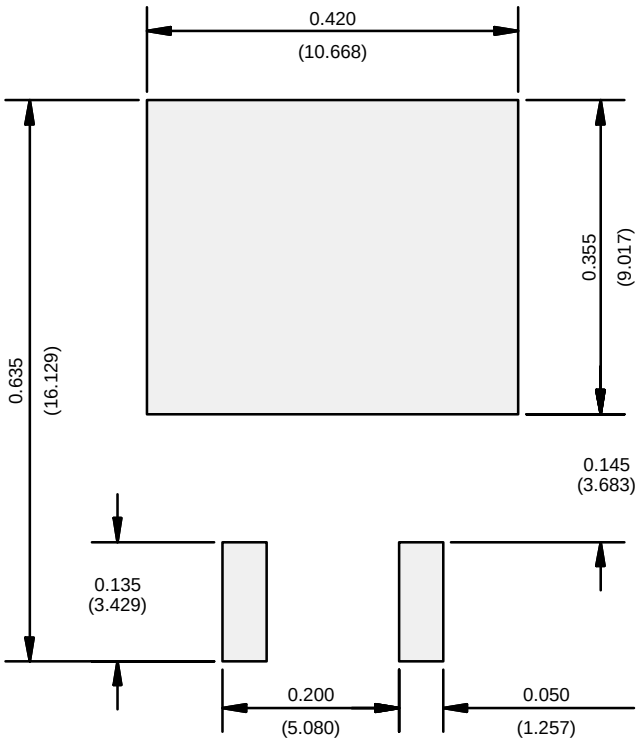

SECTION A-A

| DIM. | | INCHES | | MILLIMETERS | |
|---|---|---|---|---|---|
| | | MIN. | MAX. | MIN. | MAX. |
| A | | 0.160 | 0.190 | 4.064 | 4.826 |
| b | | 0.020 | 0.039 | 0.508 | 0.990 |
| b1 | | 0.020 | 0.035 | 0.508 | 0.889 |
| b2 | | 0.045 | 0.055 | 1.143 | 1.397 |
| c* | Thin lead | 0.013 | 0.018 | 0.330 | 0.457 |
| | Thick lead | 0.023 | 0.028 | 0.584 | 0.711 |
| c1 | Thin lead | 0.013 | 0.017 | 0.330 | 0.431 |
| | Thick lead | 0.023 | 0.027 | 0.584 | 0.685 |
| c2 | | 0.045 | 0.055 | 1.143 | 1.397 |
| D | | 0.340 | 0.380 | 8.636 | 9.652 |
| D1 | | 0.220 | 0.240 | 5.588 | 6.096 |
| D2 | | 0.038 | 0.042 | 0.965 | 1.067 |
| D3 | | 0.045 | 0.055 | 1.143 | 1.397 |
| D4 | | 0.044 | 0.052 | 1.118 | 1.321 |
| E | | 0.380 | 0.410 | 9.652 | 10.414 |
| E1 | | 0.245 | - | 6.223 | - |
| E2 | | 0.355 | 0.375 | 9.017 | 9.525 |
| E3 | | 0.072 | 0.078 | 1.829 | 1.981 |
| e | | 0.100 BSC | | 2.54 BSC | |
| K | | 0.045 | 0.055 | 1.143 | 1.397 |
| L | | 0.575 | 0.625 | 14.605 | 15.875 |
| L1 | | 0.090 | 0.110 | 2.286 | 2.794 |
| L2 | | 0.040 | 0.055 | 1.016 | 1.397 |
| L3 | | 0.050 | 0.070 | 1.270 | 1.778 |
| L4 | | 0.010 BSC | | 0.254 BSC | |
| M | | - | 0.002 | - | 0.050 |
| ECN: T13-0707-Rev. K, 30-Sep-13<br>DWG: 5843 | | | | | |

**Notes**

1. Plane B includes maximum features of heat sink tab and plastic.
2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
3. Pin-to-pin coplanarity max. 4 mils.
4. *: Thin lead is for SUB, SYB.
   Thick lead is for SUM, SYM, SQM.
5. Use inches as the primary measurement.
6. This feature is for thick lead.

## RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead




Recommended Minimum Pads
Dimensions in Inches/(mm)

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